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IN THE UNITED STATES PATENT & TRADEMARK OFFICE

APPLICANT: Dong Suk SHIN)
SERIAL NO: 10/034,243) Group Art Unit:
FILING DATE: December 28, 2001) 2812
TITLE: METHOD OF FABRICATING A SEMICONDUCTOR)
DEVICE HAVING REDUCED CONTACT RESISTANCE)

The Commissioner for Patents
Washington, D.C. 20231

REQUEST FOR CORRECTION OF FILING DATE
& CORRECTED FILING RECEIPT

Dear Sir:

The official filing receipt has been received from the Patent Office in the above application.

This application was filed via Express Mail on December 28, 2001. Attached is a copy of the Express Mail Label No. EL698183562US. Also attached is a copy of the shipment history from the U.S. Postal Service's website (www.usps.com) indicating that the contents of Express Mail Label No. EL698183562US was accepted at 5:22 pm on December 28, 2001. Accordingly, correction of the filing date of December 28, 2001 is respectfully requested.

It is believed that no fee is due since the aforesaid correction of the filing date is not due to any error by the applicant and issuance of a corrected filing receipt is respectfully requested.

Respectfully submitted,

April 8, 2002

Date

/22


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UNITED STATES PATENT AND TRADEMARK OFFICE

COMMISSIONER FOR PATENTS
UNITED STATES PATENT AND TRADEMARK OFFICE
WASHINGTON, D.C. 20231
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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	RECEIVED	ATTY. DOCKET NO.	DRAWINGS	TOT CLAIMS	IND CLAIMS
10/034,243	01/08/2002	2812	758E	CU-2760 VE	2	21	2

26530
LADAS & PARRY
224 SOUTH MICHIGAN AVENUE, SUITE 1200
CHICAGO, IL 60604

12/28/02



CONFIRMATION NO. 9124

FILING RECEIPT



0C000000007664594

Date Mailed: 03/18/2002

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Dong Suk Shin, Kyoungki-do, KOREA, REPUBLIC OF;

Domestic Priority data as claimed by applicant

Foreign Applications

REPUBLIC OF KOREA 2001-54512 09/05/2001

If Required, Foreign Filing License Granted 03/18/2002

Projected Publication Date: 03/06/2003

Non-Publication Request: No

Early Publication Request: No

Title

Method of fabricating a semiconductor device having reduced contact resistance

Preliminary Class

438

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